Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-02-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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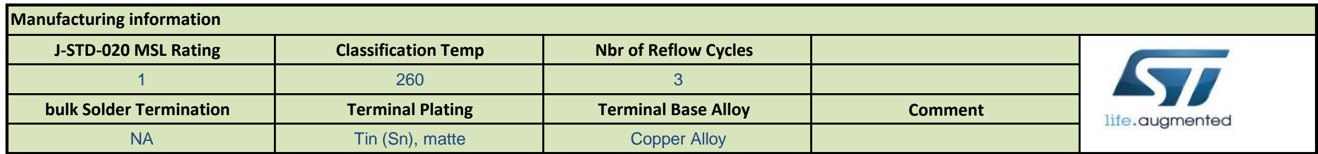
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BHDP*W1G088C	A	998G	2018-02-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	320	mg	Each	ECOPACK2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	Package: TO 252 DPAK - MDF valid for CPs: T835-800B-TR and T835-800B			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**TRUE**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : California Prop65 list, dated 15th December 2017			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			**FALSE**
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**TRUE**
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.16	Die / Leadframe	3631
Lead	5.04	Soft solder	15750
Lead-Borate Glass	0.73	Die Glass coating	2291

QueryList : REACH-15th January 2018				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**BHDP*W1G088C**					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	4.580	mg	supplier	die	Silicon (Si)	7440-21-3		3.593	mg	784498	11228
				supplier	metallization	Aluminium (Al)	7429-90-5		0.125	mg	27293	391
				supplier	metallization	Gold (Au)	7440-57-5		0.014	mg	3057	44
				supplier	metallization	Nickel (Ni)	7440-02-0		0.022	mg	4803	69
				supplier	Passivation	Silicon Oxide	7631-86-9		0.033	mg	7205	103
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.020	mg	4367	63
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1528	22
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.033	mg	7205	103
				JIG - R & California 65	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.733	mg	160044	2291
Leadframe	M-004 Copper and its alloys	166.052	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.730	mg	992039	514781
				supplier	alloy	Iron (Fe)	7439-89-6		0.165	mg	994	516
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.050	mg	300	155
				supplier	metallization	Nickel (Ni)	7440-02-0		1.107	mg	6667	3459
Soft solder	Solder	4.510	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.307	mg	954989	13459
				supplier	solder	Silver (Ag)	7440-22-4		0.113	mg	25055	353
				supplier	solder	Tin (Sn)	7440-31-5		0.090	mg	19956	281
Bonding wires	M-011 Other inorganic materials	0.923	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.923	mg	1000000	2884
Encapsulation	M-011 Other inorganic materials	142.890	mg	supplier	mold compound	Silica, vitreous	60676-86-0		128.244	mg	897502	400763
				supplier	mold compound	Epoxy resin	25068-38-6		10.002	mg	69998	31256
				supplier	mold compound	Phenol resin	29690-82-2		4.287	mg	30002	13397
				supplier	mold compound	carbon black	1333-86-4		0.357	mg	2498	1116
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266